

# SLC/BLC Inline **Leading in Vapor Phase Technology**

Premium Vapor Phase Soldering Series for Highest Demands



## The Machine

The SLC/BLC reflow vapor phase soldering systems (available as batch or inline) are perfect for medium to high volume production. The machines offer highest quality performances with smallest footprints.

Many patented features are available and provide a wide range of flexibility

## Overview

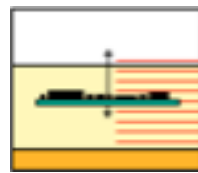
- 11 machine types for different board sizes
- Small footprint
- 2-chamber design
- Oxygen free soldering
- No overheating of components
- Low power consumption

## Standard Equipment / Specification

- Comfortable operation with Touch Screen
- Automatic carrier in- and output
- Program memory up to 50 programs
- Wide variety of adjustable solder profiles
- Low fluid consumption with 2-chamber design and fluid recovery
- Integrated cooling fan for board cooling
- Minimum maintenance and wear due to „cool handling“ (all moving parts outside the process chamber)
- 4 internal channels for comfortable temperature measuring and profiling
- Energy management system
- Fluid level check
- Automatic liquid filtering
- Integrated illumination of the soldering area

## Special features

- IPS, Intelligent Profiling System incl.
  - Soft Vapor Temperature Control (SVTC), temperature regulated profiles
  - Pilot Mode, set-up and profiling in one step
- Lead-free and leaded soldering with one fluid only, with different maximum temperatures
- Built-in software profiling capability
- Syncro-Mode
- Maintenance-free transport system (patented)
- Easy access to process chamber



Easily programmable vapor steps allow optimum adjustments of gradients

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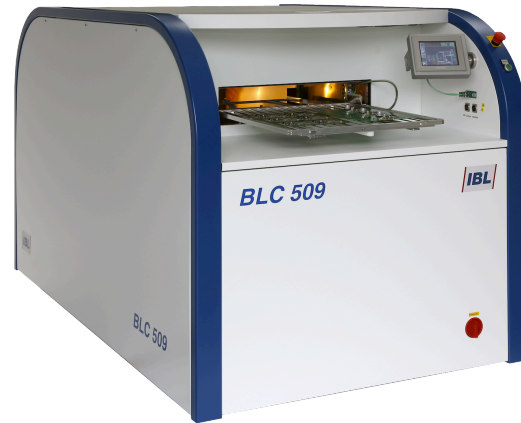
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## Options

- RCS Rapid Cooling System (patented)
- IR heater system (patented)
- VP-Control for convenient documentation and fine adjustment of the process
- Integrated PC-System
- Barcode-system for automatic program-change, traceability and unlimited program storage
- Measurement channels for board temperature recording
- Multi-Level-Mode for easy changeover between different solder heights
- Anti Fog System (AFS) for clear vision of the soldering process (patented)
- Adapter for double sided PCB boards
- UPS, uninterruptible power supply
- Inline-handling
- Closed-loop-chiller



Batch system available

Technical Data	SLC509i	SLC609i	SLC809i	BLC509i	BLC609i	BLC809i
Length (over all)	1720 mm	2020 mm	2220 mm	1720 mm	2020 mm	2220 mm
Depth	2290 mm	2290 mm	2290 mm	2490 mm	2490 mm	2490 mm
Height	1470 mm	1470 mm	1470 mm	1470 mm	1470 mm	1470 mm
Weight	730 kg	830 kg	1010 kg	790 kg	920 kg	1070 kg
Loading/unloading level, approx.	900-1000 mm					
Carrier size (in mm)	550 x 350	650 x 350	850 x 350	550 x 540	650 x 540	850 x 540
Max. board size Inline (in mm)	530 x 309 x 65	630 x 309 x 65	630 x 309 x 65	530 x 400 x 65	630 x 400 x 65	630 x 400 x 65
Liquid agent filling	15 kg	15 kg	20 kg	20 kg	20 kg	25kg
Water connection	1/2" / 2,5-5 bar					
	2,5l/min	3l/min	3,5l/min	3l/min	3l/min	3,5l/min
Max. heating capacity	5,2 kW	6,5 kW	7,8 kW	7,8 kW	7,8 kW	9,1 kW
Ø power consumption	2,1 kW/h	2,6 kW/h	3,1 kW/h	3,1 kW/h	3,2 kW/h	3,6 kW/h
Power supply	400 / 230 VAC, 50Hz					
Main fuse	20A "gl" or "C"		25A "gl" or "C"			32A "gl" or "C"

- Technical changes reserved -

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